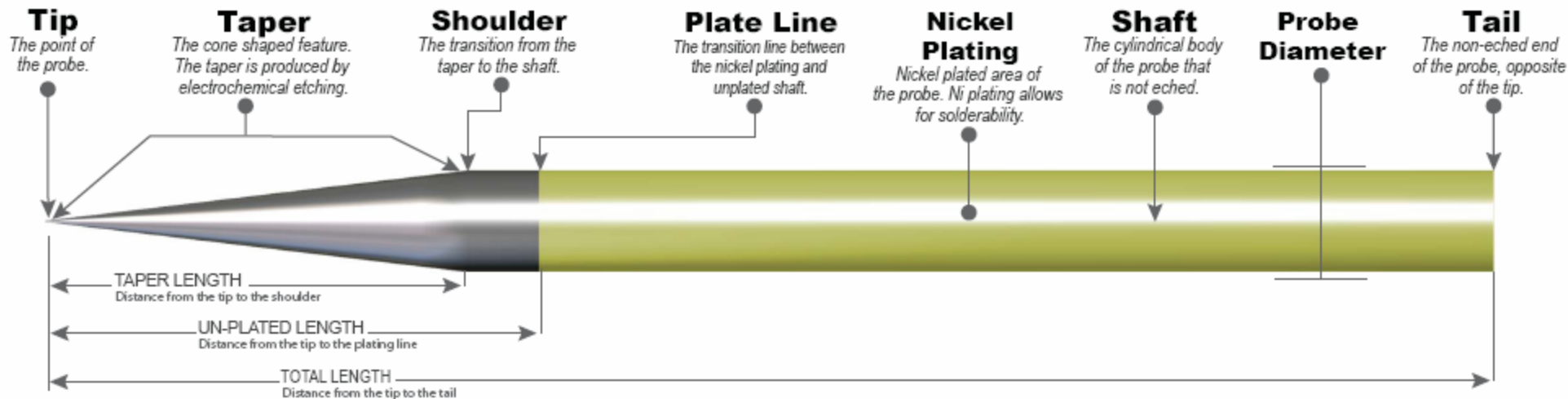
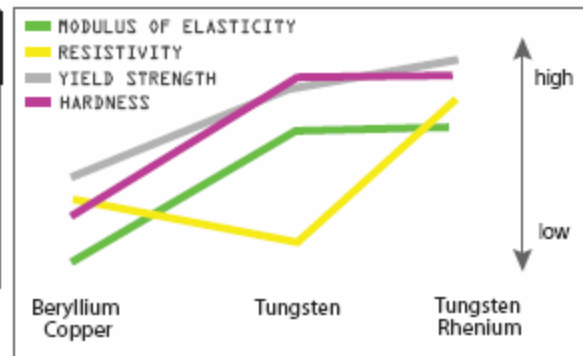


Semiconductor Probe Needles: Part Number Definition, Material Properties and Measuring Style

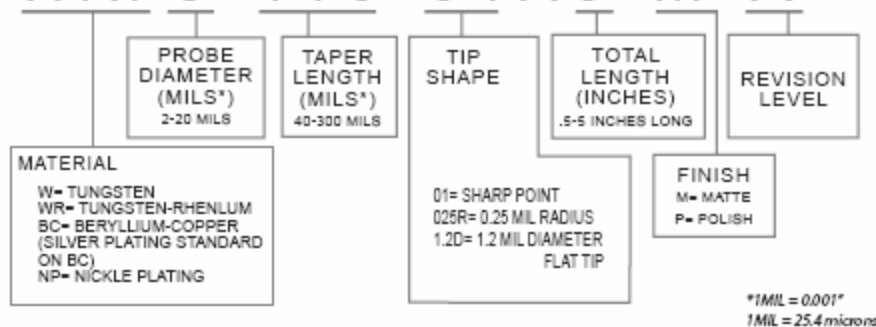


Material	CODE	DENSITY g/cm ³	RESISTIVITY μΩ/CM	YIELD STRENGTH MPa	HARDNESS KN00P	MODULUS OF ELASTICITY GPa	COMPOSITION	PROPERTIES
Beryllium Copper	(BC)	8.2	6.0	1640	325	131	Copper 98.00%, Beryllium 1.90%	Softer than tungsten, low contact resistance, high electrical conductivity
Tungsten	(W)	19.3	5.65	2900	800	400	Tungsten 99.95%	Hard material, high contact resistance, low fatigue
Tungsten Rhenium	(WR)	19.3	9.65	3360	815	410	Tungsten 98.67%, Rhenium 3.30%	Hardest material, higher contact resistance than pure tungsten



Example Part Number

WNP5 - 110 - 01 X 3 - M - A



Taper Control

